

Notice of References Cited	Application/Control No. 10/539,260		Applicant(s)/Patent Under Reexamination HAISMA, JAN	
	Examiner JONATHAN C. LANGMAN		Art Unit 1794	Page 1 of 1

U.S. PATENT DOCUMENTS

*		Document Number Country Code-Number-Kind Code	Date MM-YYYY	Name	Classification
*	A	US-5,552,345	09-1996	Schrantz et al.	438/460
*	B	US-6,417,075	07-2002	Haberger et al.	438/459
*	C	US-6,544,863	04-2003	Chong et al.	438/455
	D	US-			
	E	US-			
	F	US-			
	G	US-			
	H	US-			
	I	US-			
	J	US-			
	K	US-			
	L	US-			
	M	US-			

FOREIGN PATENT DOCUMENTS

*		Document Number Country Code-Number-Kind Code	Date MM-YYYY	Country	Name	Classification
	N	WO 9967820	12-1999	Germany	Haberger et al.	H01L 21/20,78
	O					
	P					
	Q					
	R					
	S					
	T					

NON-PATENT DOCUMENTS

*		Include as applicable: Author, Title Date, Publisher, Edition or Volume, Pertinent Pages)
	U	Spiering et al. "Sacrificial wafer bonding for planarization after very deep wafer etching" all teach the structures being formed in the handle wafer and not being formed of the intermediate or insulating layer". Journal of Mircroelectromechanical Systems., vol. 4, no.3, 1995, pgs 151-157.
	V	
	W	
	X	

*A copy of this reference is not being furnished with this Office action. (See MPEP § 707.05(a).)
Dates in MM-YYYY format are publication dates. Classifications may be US or foreign.